

Plastronics has the burn-in socket for every technology road you travel!



Wherever your technology path leads, Plastronics Socket Company has the right test and burn-in socket solution.



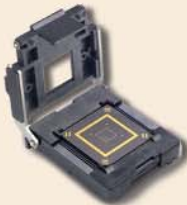
Plastronics offers the widest range of sockets for QFN devices:

Pitch options: 0.40, 0.50, 0.65, 0.80 and 1.00 mm pitches with custom pitches down to 0.30 mm. Sockets for device sizes ranging from 1.5 mm to 16 mm. Lidded and Open Top (OTQFN) sockets. Optional custom heat slug available for thermal management.



Plastronics offers an extensive range of sockets for fine pitch BGA devices:

Pitch options: 0.80, 0.75, 0.65 and 0.50 mm pitches. Contact technology: dual "pinch" style Au plated BeCu contacts. 0.50 mm pitch sockets up to 20 x 20 ball matrix with max IC size of 11.5 x 18.0 mm. 0.65 mm pitch sockets up to 25 x 25 ball matrix with max IC size of 18.0 x 18.0 mm. 0.75 mm pitch sockets up to 10 x 19 ball matrix with max IC size of 10.2 x 20.0 mm. 0.80 mm pitch sockets, 3 body sizes available, up to 16 x 20 ball matrix.



Additionally, Plastronics offers custom solutions for Thermal Management of BGA devices, a wide range of LCC, PLCC, SOIC and TSOP sockets, and the ONLY Pressure-Mount TQFP sockets in the industry today.

Quality to meet your strict requirements.

Commitment to meet your delivery needs.

Consistency to be here for you yesterday, today and tomorrow.



For a complete listing of all ball matrixes and IC device sizes for each package type, please visit our website at www.PlastronicsUSA.com or call: 800-582-5822.

Plastronics Socket Company 2601 Texas Drive Irving, TX 75062

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